

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: R. IKEZAWA, et al.
Application No.: 10/552,441
Filed: OCTOBER 7, 2005
For: ENCAPSULATING EPOXY RESIN MOLDING MATERIAL, AND SEMICONDUCTOR DEVICE
Group AU: 2815
Examiner: Scott E. Bauman
Confirm. No.: 7255

PETITION FOR EXTENSION OF TIME

Mail Stop: Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

August 27, 2007

Sir:

In the matter of the above-identified application, applicants hereby respectfully petition for an extension of time to permit filing a response within the first month subsequent to expiration of the shortened statutory period set in the outstanding Office Action mailed April 25, 2007. An electronic payment in the amount of \$120.00 to cover the required fee for the requested extension of time is being submitted herewith.

It is respectfully requested that any shortage in the fee be charged to the account of Antonelli, Terry, Stout & Kraus, LLP, Account No. 01-2135 (Case No. 1204.45467X00).

Respectfully submitted,

ANTONELLI, TERRY STOUT & KRAUS, LLP

/William I. Solomon/
William I. Solomon
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WIS/slk